



OCTOBER 12-15, 2025 | SCOTTSDALE, ARIZONA, USA

CONFIRMED PLENARY AND INVITED SPEAKERS

Authors	Affiliation	Title
Chuck Campbell	Qorvo	Plenary: Adapting, Self-Configuring and Reconfigurable Circuits and MMICs
Tom Winslow	MACOM	Introduction to the WSProbe
Xugang Ke	Zhejiang University	A 100V VIN 400W GaN Buck-Boost Converter with Adaptive Frequency Modulation and GaN Hard-Short Protection Achieving 98.6% Efficiency for Photovoltaic to Solid-State Battery System
Qiang Yu	Intel	Evolution of 300mm GaN-on-Si Technology with Monolithically Integrated Si PMOS: From Technology Development to RF and mmWave Circuit Demonstrations
Nicholas Miller	Michigan State	Simulating High-Voltage RF GaN HEMTs using Fermi Kinetics Transport
Dr. Petros Beleniotis	Brandenburg University of Technology	Traps in GaN HEMTs: From Characterization to Model Development and Device Optimization
Jeff Johnson	Globalfoundries	Technology CAD and Machine Learning: A New Paradigm for Semiconductor Technology Development
Christoph Weimer	TU Dresden	Long-Term RF Reliability of SiGe HBTs: Characterization and Modeling
Naftali Weiss	Ciena	200 GBaud single-carrier coherent optical transmission
Matthew Streshinsky	Luminous Computing	53 GBaud NRZ/PAM-4 Monolithic Opto-Electrical Transceiver in a 45nm CMOS-Silicon Photonic Process with Embedded Controller

Patrick Reynaert	KU Leuven	Polymer Microwave Fiber: Redefining the Limits of Low-Power and High-Speed Communication
Prof. Aritra Banerjee	University of Illinois Chicago, USA	Active Load Modulation for Back-Off Efficiency Improvement in Millimeter-Wave Power Amplifiers in CMOS, SiGe, and III-V Technologies
Dr. Akihito Hirai	Mitsubishi Electric	Terahertz Sensing using CMOS-RFIC with High-efficiency Power Amplifier
Dr. Payam Heydari	UC Irvine	Innovations for 6G and Beyond: mm-Wave Wideband Digital Beamforming Transceiver Arrays for Integrated Sensing and Communication
Dr. Amirreza Alizadeh	Keysight	High-Efficiency mm-Wave H-Band Power Amplifiers with Over 20% PAE
Michael Thompson	Cadence/Synopsys; CEA Leti	Heterogeneous integration of advanced 2.5D and 3D ICs
S. Andreev, K. Herman, G. D. Pietrantonio	IHP GmbH	IHP OpenPDK Initiative: Bringing Open Source to Analog and RF Design
Julio Costa	Globalfoundries	3DIC Technologies for RF Mobile and Infrastructure Applications
Said Rami	Intel	Advancing Next Generation Wireless with Scaled FinFET Technologies.